

Search Notes



Application No.

09/896,786

Examiner

Allan Olsen

Applicant(s)

HWANG ET AL.

Art Unit

1763

SEARCHED

SEARCH NOTES (INCLUDING SEARCH STRATEGY)

INTERFERENCE SEARCHED

| INTERFERENCE SEARCHED | | | |
|------------------------------|-----------------|-------------|-----------------|
| Class | Subclass | Date | Examiner |
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| L Number | Hits | Search Text | DB | Time stamp |
|----------|------|---|-----------------------------------|------------------|
| - | 6563 | (etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric)) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2001/04/09 02:21 |
| - | 2454 | ((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:00 |
| - | 20 | ((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric))) and ((etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4)) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2001/04/09 02:27 |
| - | 46 | ((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4)) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2001/04/09 03:22 |
| - | 60 | ((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4))) (((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$ temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4))) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/05/27 03:56 |
| - | 0 | "09/124,291" | US-PGPUB | 2002/03/18 14:40 |
| - | 1 | "09124291" | US-PGPUB | 2002/03/18 14:41 |
| - | 0 | "09124291" and pressure near bear\$3 | US-PGPUB | 2002/03/18 14:44 |
| - | 1 | "09124291" and pressure | US-PGPUB | 2002/03/18 14:46 |
| - | 0 | "09124291" and bear\$3 | US-PGPUB | 2002/03/18 14:46 |
| - | 9 | (US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$).did. | USPAT | 2003/05/27 03:37 |
| - | 76 | ((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4))) (((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4))) | USPAT; EPO; JPO; DERWENT; IBM_TDB | 2003/05/27 03:54 |

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|--|----|--|---|------------------|
| | 60 | (US-5772832-\$ or US-5716870-\$ or US-5707487-\$ or US-5254821-\$ or US-5192849-\$ or US-5185506-\$ or US-5147968-\$ or US-5137991-\$ or US-5132282-\$ or US-5130294-\$ or US-5125358-\$ or US-5114770-\$ or US-3638061-\$ or US-5879973-\$ or US-5866213-\$ or US-5665640-\$ or US-5653812-\$ or US-5639341-\$ or US-5567243-\$ or US-5563182-\$ or US-5538699-\$ or US-5527391-\$ or US-5514217-\$ or US-4609428-\$ or US-4842708-\$ or US-4883686-\$).did. or (US-4937094-\$ or US-4985114-\$ or US-5023056-\$ or US-5061838-\$ or US-5079334-\$ or US-5487875-\$ or US-5482611-\$ or US-5470768-\$ or US-5463014-\$ or US-5439533-\$ or US-5368685-\$ or US-5296036-\$ or US-5294694-\$ or US-5256846-\$ or US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6090303-\$ or US-6117279-\$ or US-6136685-\$ or US-6124834-\$ or US-5983906-\$ or US-5968379-\$ or US-6200911-\$ or US-6207901-\$ or US-6197166-\$).did. or (US-6190513-\$ or US-6189482-\$ or US-6178920-\$ or US-6173673-\$ or US-6158384-\$ or US-6139923-\$ or US-5994678-\$).did. | USPAT | 2003/05/27 03:56 |
| | 16 | ((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4))) ((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4))) not ((US-5772832-\$ or US-5716870-\$ or US-5707487-\$ or US-5254821-\$ or US-5192849-\$ or US-5185506-\$ or US-5147968-\$ or US-5137991-\$ or US-5132282-\$ or US-5130294-\$ or US-5125358-\$ or US-5114770-\$ or US-3638061-\$ or US-5879973-\$ or US-5866213-\$ or US-5665640-\$ or US-5653812-\$ or US-5639341-\$ or US-5567243-\$ or US-5563182-\$ or US-5538699-\$ or US-5527391-\$ or US-5514217-\$ or US-4609428-\$ or US-4842708-\$ or US-4883686-\$).did. or (US-4937094-\$ or US-4985114-\$ or US-5023056-\$ or US-5061838-\$ or US-5079334-\$ or US-5487875-\$ or US-5482611-\$ or US-5470768-\$ or US-5463014-\$ or US-5439533-\$ or US-5368685-\$ or US-5296036-\$ or US-5294694-\$ or US-5256846-\$ or US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6090303-\$ or US-6117279-\$ or US-6136685-\$ or US-6124834-\$ or US-5983906-\$ or US-5968379-\$ or US-6200911-\$ or US-6207901-\$ or US-6197166-\$).did. or (US-6190513-\$ or US-6189482-\$ or US-6178920-\$ or US-6173673-\$ or US-6158384-\$ or US-6139923-\$ or US-5994678-\$).did.) | USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/27 03:57 |

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| - | 9 | ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$).did.) and (((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4))) (((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 02:04 |
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| - | 25 | <p>((((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4)))</p> <p>((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4)))</p> <p>not ((US-5772832-\$ or US-5716870-\$ or US-5707487-\$ or US-5254821-\$ or US-5192849-\$ or US-5185506-\$ or US-5147968-\$ or US-5137991-\$ or US-5132282-\$ or US-5130294-\$ or US-5125358-\$ or US-5114770-\$ or US-3638061-\$ or US-5879973-\$ or US-5866213-\$ or US-5665640-\$ or US-5653812-\$ or US-5639341-\$ or US-5567243-\$ or US-5563182-\$ or US-5538699-\$ or US-5527391-\$ or US-5514217-\$ or US-4609428-\$ or US-4842708-\$ or US-4883686-\$). did. or (US-4937094-\$ or US-4985114-\$ or US-5023056-\$ or US-5061838-\$ or US-5079334-\$ or US-5487875-\$ or US-5482611-\$ or US-5470768-\$ or US-5463014-\$ or US-5439533-\$ or US-5368685-\$ or US-5296036-\$ or US-5294694-\$ or US-5256846-\$ or US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6090303-\$ or US-6117279-\$ or US-6136685-\$ or US-6124834-\$ or US-5983906-\$ or US-5968379-\$ or US-6200911-\$ or US-6207901-\$ or US-6197166-\$). did. or (US-6190513-\$ or US-6189482-\$ or US-6178920-\$ or US-6173673-\$ or US-6158384-\$ or US-6139923-\$ or US-5994678-\$). did.) (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$). did.) and (((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4)))</p> <p>((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4))))</p> <p>(US-6280563-\$ or US-6231776-\$ or US-6189482-\$ or US-6136685-\$ or US-6051286-\$ or US-6036878-\$). did.</p> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 01:59 |
| - | 6 | | USPAT | 2003/05/29 01:58 |

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| | | 4 | ((US-6280563-\$ or US-6231776-\$ or US-6189482-\$ or US-6136685-\$ or US-6051286-\$ or US-6036878-\$).did.) and ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$).did.) and (((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((hinder block impede stop interfere) near (RF microwave inducti\$4))) (((((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$4 temperature near (window wall surface dielectric))) and (etch\$3 deposit\$4) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and ((prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4)))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 02:08 |
| | | 6 | ((US-6280563-\$ or US-6231776-\$ or US-6189482-\$ or US-6136685-\$ or US-6051286-\$ or US-6036878-\$).did.) and ((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) (RF microwave inducti\$4 heat\$4 temperature) near (window wall surface dielectric) (hinder block impede stop interfere) near (RF microwave inducti\$4) (prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 04:30 |
| | | 4 | (("6280563") or ("6136685")).PN. | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 04:32 |
| | | 1 | ((("6280563") or ("6136685")).PN.) and (Pt platinum) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 04:50 |
| | | 2 | ((US-6280563-\$ or US-6231776-\$ or US-6189482-\$ or US-6136685-\$ or US-6051286-\$ or US-6036878-\$).did.) and ((etch\$3 deposit\$4) near (metal\$3 pt cu al ti ru ir conduct\$3) (RF microwave inducti\$4 heat\$4 temperature) near (window wall surface dielectric) (hinder block impede stop interfere) near (RF microwave inducti\$4) (prevent\$3 diminish\$3 decreas\$3) near (RF microwave inducti\$4))) and (Pt platinum) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 04:50 |
| | | 2 | ((("6280563") or ("6136685")).PN.) and heat\$3 | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2003/05/29 04:50 |
| | | 11 | (US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did. | USPAT | 2004/05/03 17:50 |
| | | 4 | ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 17:57 |

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| - | 60 | (US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did. or (Pt platinum) not ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum) ((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)) | USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:01 |
| - | 15 | ((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum) ((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)) | USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:17 |
| - | 3189 | ((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)) | USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB | |

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| - | 969 | ((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$) .did.) and (Pt platinum)) ((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$) .did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$) .did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$) .did.) and (Pt platinum) not ((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$) .did.) and (Pt platinum))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:08 |
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| - | 943 | <p>((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)))) and (window wall surface dielectric) and (deposit depositing deposition) and (pt platinum)</p> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:09 |
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| - | 273 | <p>((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)))) and (window wall surface dielectric) same (deposit depositing deposition) same (pt platinum)</p> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:10 |
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| - | 103 | <p>((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)))). and (window wall surface dielectric) with (deposit depositing deposition) with (pt platinum)</p> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:10 |
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| - | 8 | <p>((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)))) and (window wall surface dielectric) near2 (deposit depositing deposition) near2 (pt platinum)</p> | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:10 |
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| | 30 | (microwave inducti\$4) near3 plasma and (((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)))) and (window wall surface dielectric) with (deposit depositing deposition) with (pt platinum)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:18 |
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| - | 17 | (microwave inducti\$4) near plasma and (((((etch\$3 deposit depositing deposition) near (metal\$3 pt cu al ti ru ir conduct\$3) and (RF microwave inducti\$4) and (heat\$3 temperature near (window wall surface dielectric))) and (etch\$3 deposit depositing deposition) near ((metal\$3 pt cu al ti ru ir conduct\$3) and (window wall surface dielectric)))) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum)) (((US-5079334-\$ or US-5114770-\$ or US-5125358-\$ or US-5130294-\$ or US-5132282-\$ or US-5137991-\$ or US-5147968-\$ or US-5185506-\$ or US-3638061-\$ or US-4883686-\$ or US-4842708-\$ or US-4609428-\$ or US-6117279-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6158384-\$ or US-6173673-\$ or US-6178920-\$ or US-6189482-\$ or US-6190513-\$ or US-6197166-\$ or US-6200911-\$ or US-6207901-\$ or US-5192849-\$ or US-5254821-\$).did. or (US-5256846-\$ or US-5294694-\$ or US-5296036-\$ or US-5368685-\$ or US-5439533-\$ or US-5463014-\$ or US-5470768-\$ or US-5482611-\$ or US-5487875-\$ or US-5514217-\$ or US-5527391-\$ or US-5538699-\$ or US-5563182-\$ or US-5567243-\$ or US-5639341-\$ or US-5653812-\$ or US-5665640-\$ or US-5707487-\$ or US-5716870-\$ or US-5772832-\$ or US-5866213-\$ or US-5879973-\$ or US-5968379-\$ or US-5983906-\$ or US-5994678-\$ or US-6036878-\$ or US-6051114-\$).did. or (US-6051286-\$ or US-6071372-\$ or US-6090303-\$ or US-5061838-\$ or US-5023056-\$ or US-4985114-\$ or US-4937094-\$).did.) and (Pt platinum) not (((US-6036878-\$ or US-6051286-\$ or US-6051114-\$ or US-6071372-\$ or US-6124834-\$ or US-6136685-\$ or US-6139923-\$ or US-6189482-\$ or US-6190513-\$ or US-6280563-\$ or US-6231776-\$).did.) and (Pt platinum))) and (window wall surface dielectric) with (deposit depositing deposition) with (pt platinum)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/03 18:28 |
| - | 0 | 20010050267.URPN. | USPAT | 2004/05/03 18:20 |
| - | 0 | 20030159782.URPN. | USPAT | 2004/05/03 18:27 |

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| - | 14 | etch\$3 near (Pt platinum) with (microwave inductively inductive induction) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 12:22 |
| - | 35 | etch\$3 with (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 12:23 |
| - | 17 | etch\$3 near3 (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 12:23 |
| - | 14 | etch\$3 near2 (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction)) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 12:56 |
| - | 3 | (etch\$3 near3 (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction))) not (etch\$3 near2 (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 13:00 |
| - | 18 | (etch\$3 with (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction))) not (etch\$3 near3 (Pt platinum) with (microwave inductively inductive induction) not (etch\$3 near (Pt platinum) with (microwave inductively inductive induction))) | USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB | 2004/05/04 13:01 |